

April 15, 2004

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Divisional Patent Application of
Serial No.: 10/315,534 12/10/02
ROMEO EMMANUEL P. ALVAREZ
METHOD FOR FORMING A WAFER LEVEL CHIP
SCALE PACKAGE, AND PACKAGE FORMED THEREBY

PRELIMINARY AMENDMENT

Dear Sir:

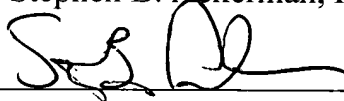
This is a preliminary amendment for the above referenced Divisional Patent Application. Please amend the above identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on April 16, 2004.

Stephen B. Ackerman, Reg. No. 37,761

Signature/Date



4/16/04